

## Materials Declaration

<b>Package</b>	TO52
<b>Body Size</b>	
<b>Lead Count</b>	3
<b>Option</b>	Au

### Cans

Item	% of Cans	Weight (g)	PPM
Nickel	100	9.87E-02	324416

### Headers

Item	% of Headers	Weight (g)	PPM
Kovar (Eyelet)	62.90	1.19 E-01	391864
Kovar(Assembly)	20.65	3.91 E-02	128648
Kovar (Spot)	9.26	1.76 E-02	57689
Nickel	3.01	5.71 E-03	18752
Glass	2.45	4.64 E-03	15263
Subtotal		1.86 E-01	612217

### Insulator

Item	% of Insulator	Weight (g)	PPM
Al2O3	91.0	2.73 E-03	8973
SiO2	6.00	1.80 E-04	592
CaO	2.00	6.00 E-05	197
MgO2	1.00	3.00 E-05	99
Subtotal		3.00 E-03	9860

### Bonding Wires

Item	% of Wire	Weight (g)	PPM
Aluminum	100.0	5.80 E-03	19063

### Chip

Item	% of Chip	Weight (g)	PPM
Si	100.0	2.20 E-03	7231

### External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Gold	100.0	3.28 E-03	10778

### Die Attach Paste

Item	% of Die Attach	Weight (g)	PPM
Poly (tetrafluoroethylene)	60.0	3.00 E-03	9860
Bismaleimide resin	30.0	1.50 E-03	4930
Synthetic resin	10.0	5.00 E-04	1643
Subtotal		5.00 E-03	16434

### Package Totals

Weight (g)	PPM
<b>3.04 E-01</b>	<b>1000000</b>

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary

## Materials Declaration

<b>Package</b>	TO52
<b>Body Size</b>	
<b>Lead Count</b>	3
<b>Option</b>	SnPb

### Cans

Item	% of Cans	Weight (g)	PPM
Nickel	100	9.87E-02	250231

### Headers

Item	% of Headers	Weight (g)	PPM
Kovar (Eyelet)	62.90	1.19 E-01	302255
Kovar(Assembly )	20.65	3.91 E-02	99230
Kovar (Spot)	9.26	1.76 E-02	44497
Nickel	3.01	5.71 E-03	14464
Glass	2.45	4.64 E-03	11773
Gold	1.73	3.28 E-03	8313
Subtotal		1.90 E-01	480532

### Insulator

Item	% of Insulator	Weight (g)	PPM
Al2O3	91.0	2.73 E-03	6921
SiO2	6.00	1.80 E-04	456
CaO	2.00	6.00 E-05	152
MgO2	1.00	3.00 E-05	76
Subtotal		3.00 E-03	7606

### Bonding Wires

Item	% of Wire	Weight (g)	PPM
Aluminum	100.0	5.80 E-03	14704

### Chip

Item	% of Chip	Weight (g)	PPM
Si	100.0	2.20 E-03	5577

### External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	63.00	5.92 E-02	150134
Pb	37.00	3.48 E-02	88174
Subtotal		9.40 E-02	238308

### Preform 1

Item	% of Preform 1	Weight (g)	PPM
Gold	98.0	1.08 E-03	2733
Silicon	2.0	2.20 E-05	56
Subtotal		1.10 E-03	2789

### Preform 2

Item	% of Preform 2	Weight (g)	PPM
Gold	99.99	1.00 E-04	253

### Package Totals

Weight (g)	PPM
3.94 E-01	1000000

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